

PRELIMINARY

MITSUBISHI LSI's M5M416165CJ, TP-5, -6, -7, -5S, -6S, -7S

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

DESCRIPTION

This is a family of 1048576-word by 16-bit dynamic RAMS, fabricated with the high performance CMOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential.

The use of double-layer metal process combined with twin-well CMOS technology and a single-transistor dynamic storage stacked capacitor cell provide high circuit density at reduced costs. Multiplexed address inputs permit both a reduction in pins and an increase in system densities.

FEATURES

Type name	RAS access time (max. ns)	CAS access time (max. ns)	Address access time (max. ns)	OE access time (max. ns)	Cycle time (min. ns)	Power dissipation (typ. mW)
M5M416165CXX-5,-5S	50	13	25	13	90	540
M5M416165CXX-6,-6S	60	15	30	15	110	430
M5M416165CXX-7,-7S	70	20	35	20	130	385

XX=J,TP

- Standard 42 pin SOJ, 50 pin TSOP
- Single 5.0V $\pm 10\%$ supply
- Low stand-by power dissipation
5.5mW (Max) ----- CMOS Input level
- Low operating power dissipation
M5M416165Cxx-5,-5S ----- 660.0mW (Max)
M5M416165Cxx-6,-6S ----- 525.0mW (Max)
M5M416165Cxx-7,-7S ----- 470.0mW (Max)
- Hyper-page mode, Read-modify-write, RAS-only refresh
CAS before RAS refresh, Hidden refresh capabilities
- Early-write mode, OE and W to control output buffer impedance
All inputs, output TTL compatible and low capacitance
- 4096 refresh cycles every 64ms (A₀~A₁₁)
* : Applicable to self refresh version (M5M416165CJ, TP-5S, -6S, -7S : option) only

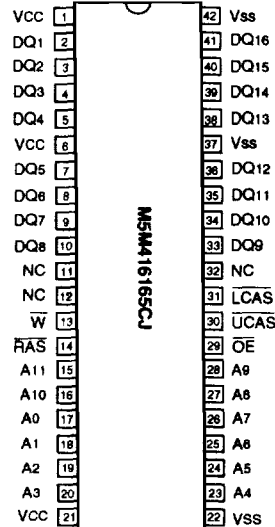
APPLICATION

Main memory unit for computers, Microcomputer memory,
Refresh memory for CRT

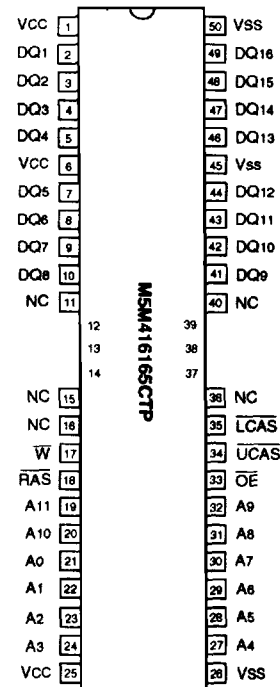
PIN DESCRIPTION

Pin name	Function
A ₀ ~A ₁₁	Address inputs
DQ ₁ ~DQ ₁₆	Data inputs/outputs
RAS	Row address strobe input
UCAS	Upper byte control column address strobe input
LCAS	Lower byte control column address strobe input
W	Write control input
OE	Output enable input
Vcc	Power supply (+5.0V)
Vss	Ground (0V)

PIN CONFIGURATION (TOP VIEW)



Outline 42P0N-A (400mil SOJ)



Outline 50P3G-F (400mil TSOP Normal Bend)

NC : NO CONNECTION

PRELIMINARY

M5M416165CJ,TP-5,-6,-7,-5S,-6S,-7S

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

FUNCTION

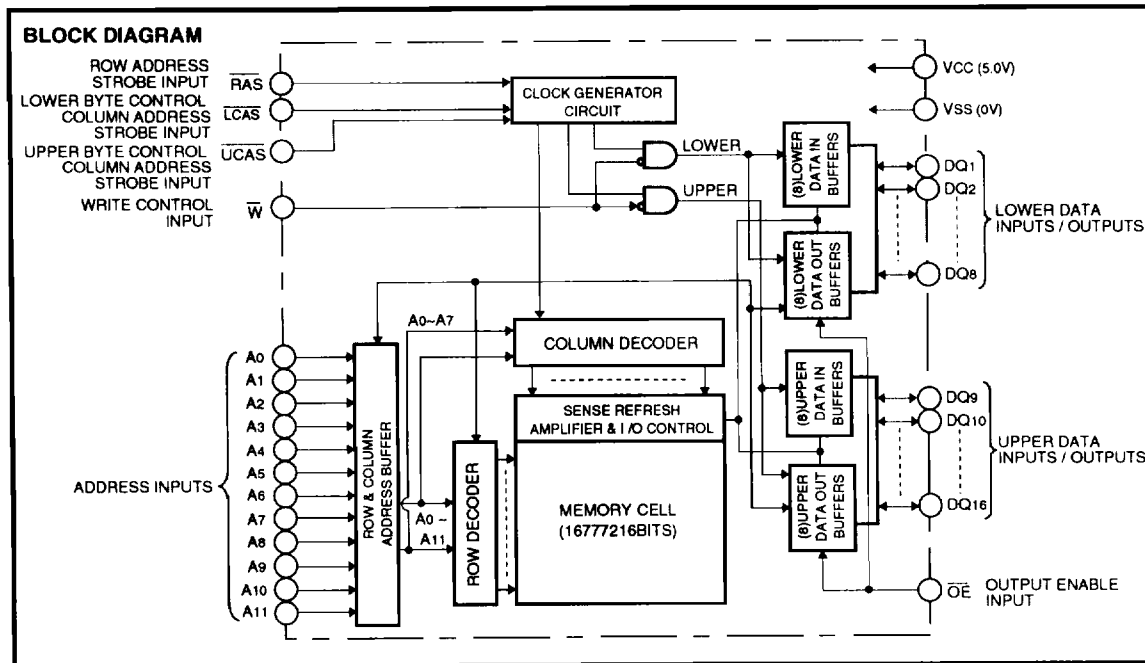
The M5M416165CJ, TP provide, in addition to normal read, write, and read-modify-write operations, a number of other functions, e.g.,

hyper page mode, $\overline{\text{RAS}}$ -only refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs					Input/Output	
	RAS	LCAS	UCAS	W	$\overline{\text{OE}}$	DQ1-DQ8	DQ9-DQ16
Lower byte read	ACT	ACT	NAC	NAC	ACT	DOUT	OPN
Upper byte read	ACT	NAC	ACT	NAC	ACT	OPN	DOUT
Word read	ACT	ACT	ACT	NAC	ACT	DOUT	DOUT
Lower byte write	ACT	ACT	NAC	ACT	NAC	DIN	DNC
Upper byte write	ACT	NAC	ACT	ACT	NAC	DNC	DIN
Word write	ACT	ACT	ACT	ACT	NAC	DIN	DIN
RAS-only refresh	ACT	NAC	NAC	DNC	DNC	OPN	OPN
Hidden refresh	ACT	ACT	ACT	NAC	ACT	DOUT	DOUT
CAS before RAS refresh	ACT	ACT	ACT	DNC	DNC	OPN	OPN
Stand-by	NAC	DNC	DNC	DNC	DNC	OPN	OPN

Note : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, IVD : invalid, APD : applied, OPN : open



PRELIMINARY
 This is a preliminary drawing. Specifications and other details are subject to change without notice.

M5M416165CJ,TP-5,-6,-7,-5S,-6S,-7S

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Supply voltage	With respect to V _{SS}	-1~7	V
V _I	Input voltage		-1~7	V
V _O	Output voltage		-1~7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a =25°C	1000	mW
T _{opr}	Operating temperature		0 ~ 70	°C
T _{stg}	Storage temperature		-65 ~ 150	°C

RECOMMENDED OPERATING CONDITIONS (T_a=0~70°C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{SS}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.0	V
V _{IL}	Low-level input voltage, all inputs	-1		0.8	V

Note 1: All voltage values are with respect to V_{SS}.

ELECTRICAL CHARACTERISTICS (T_a=0~70°C, V_{CC}=5.0V±10%, V_{SS}=0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit	
			Min	Typ	Max		
V _{OH}	High-level output voltage	I _{OH} =-5.0mA	2.4		V _{CC}	V	
V _{OL}	Low-level output voltage	I _{OL} =4.2mA	0		0.4	V	
I _{OZ}	Off-state output current	Q floating 0V ≤ V _{OUT} ≤ 5.5V	-10		10	μA	
I _I	Input current	0V ≤ V _{IN} ≤ 6V, Other inputs pins=0V	-10		10	μA	
I _{CC1(AV)}	Average supply current from V _{CC} operating (Note 3,4,5)	M5M416165C-5,-5S	R _{AS} , C _{AS} cycling t _{RC} =t _{WC} =min. output open			120	mA
		M5M416165C-6,-6S				95	
		M5M416165C-7,-7S				85	
I _{CC2}	Supply current from V _{CC} , stand-by (Note 6)	R _{AS} =C _{AS} =V _{IH} , output open				2	mA
		R _{AS} =C _{AS} ≥ V _{CC} -0.2V output open				1 0.3*	
I _{CC3(AV)}	Average supply current from V _{CC} refreshing (Note 3,5)	M5M416165C-5,-5S	R _{AS} cycling, C _{AS} =V _{IH} t _{RC} =min. output open			120	mA
		M5M416165C-6,-6S				95	
		M5M416165C-7,-7S				85	
I _{CC4(AV)}	Average supply current from V _{CC} Hyper-Page-Mode (Note 3,4,5)	M5M416165C-5,-5S	R _{AS} =V _{IL} , C _{AS} cycling t _{PC} =min. output open			165	mA
		M5M416165C-6,-6S				130	
		M5M416165C-7,-7S				110	
I _{CC6(AV)}	Average supply current from V _{CC} C _{AS} before R _{AS} refresh mode (Note 3)	M5M416165C-5,-5S	C _{AS} before R _{AS} refresh cycling t _{RC} =min. output open			120	mA
		M5M416165C-6,-6S				95	
		M5M416165C-7,-7S				85	
I _{CC8(AV) *}	Average supply current from V _{CC} Extended-refresh cycle (Note 6)	M5M416165C (S)	Stand-by: R _{AS} ≥ V _{CC} -0.2V C _{AS} ≥ V _{CC} -0.2V or C _{AS} ≤ 0.2V C _{AS} before R _{AS} refresh: R _{AS} cycling C _{AS} ≤ 0.2V or C _{AS} before R _{AS} refresh cycling W ≤ 0.2V or ≥ V _{CC} -0.2V OE ≤ 0.2V or ≥ V _{CC} -0.2V A ₀ ~A ₁₁ ≤ 0.2V or ≥ V _{CC} -0.2V DQ=open, t _{RC} =125 μs, t _{RAS} =t _{RASmin} ~1 μs			600	μA
I _{CC9(AV) *}	Average supply current from V _{CC} Self-refresh cycle	M5M416165C (S)	R _{AS} =C _{AS} ≤ 0.2V			400	μA

- Note 2: Current flowing into an IC is positive, out is negative.
 3: I_{CC1} (AV), I_{CC3} (AV) and I_{CC4} (AV) are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.
 4: I_{CC1} (AV) and I_{CC4} (AV) are dependent on output loading. Specified values are obtained with the output open.
 5: Column Address can be changed once or less while R_{AS}=V_{IL} and C_{AS}/U_{CAS}=V_{IH}.



PRELIMINARY
 Feature: This is not a final specification.
 Some parameters limits are subject to change.

M5M416165CJ,TP-5,-6,-7,-5S,-6S,-7S

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

CAPACITANCE (Ta=0~70°C, Vcc=5.0V±10%, Vss=0V, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _{I(A)}	Input capacitance, address inputs	V _I =V _{SS} f=1MHz V _I =25mVrms			5	pF
C _{I(OE)}	Input capacitance, OE input				7	pF
C _{I(W)}	Input capacitance, write control input				7	pF
C _{I(RAS)}	Input capacitance, RAS input				7	pF
C _{I(CAS)}	Input capacitance, CAS input				7	pF
C _{I/O}	Input/Output capacitance, data ports				7	pF

SWITCHING CHARACTERISTICS (Ta=0~70°C, Vcc=5.0V±10%, Vss=0V, unless otherwise noted, see notes 6,14,15)

Symbol	Parameter	Limits						Unit
		M5M416165C-5,-6S		M5M416165C-6,-6S		M5M416165C-7,-7S		
		Min	Max	Min	Max	Min	Max	
t _{CAC}	Access time from CAS (Note 7,8)		13		15		20	ns
t _{RAC}	Access time from RAS (Note 7,9)		50		60		70	ns
t _{AA}	Column address access time (Note 7,10)		25		30		35	ns
t _{CPA}	Access time from CAS precharge (Note 7,11)		30		35		40	ns
t _{OEA}	Access time from OE (Note 7)		13		15		20	ns
t _{OHC}	Output hold time from CAS	5		5		5		ns
t _{OHR}	Output hold time from RAS (Note 13)	5		5		5		ns
t _{CLZ}	Output low impedance time from CAS low (Note 7)	5		5		5		ns
t _{OEZ}	Output disable time after OE high (Note 12)	0	13	0	15	0	20	ns
t _{WEZ}	Output disable time after WE low (Note 12)	0	13	0	15	0	20	ns
t _{OFF}	Output disable time after CAS high (Note 12,13)	0	13	0	15	0	20	ns
t _{REZ}	Output disable time after RAS high (Note 12,13)	0	13	0	15	0	20	ns

Note 6: An initial pause of 500 μs is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS clock such as RAS-Only refresh).

Note the RAS may be cycled during the initial pause. And any 8 RAS or RAS/CAS cycles are required after prolonged periods (greater than 64ms) of RAS inactivity before proper device operation is achieved.

7: Measured with a load circuit equivalent to V_{OH}=2.4V(I_{OH}=-5mA) / V_{OL}=0.4V(I_{OL}=4.2mA) load 100pF.

The reference levels for measuring of output signal are 2.0V(V_{OH}) and 0.8V(V_{OL}).

8: Assumes that t_{RCD} ≥ t_{RCD(max)} and t_{ASC} ≥ t_{ASC(max)}, and t_{CP} ≥ t_{CP(max)}.

9: Assumes that t_{RCD} ≤ t_{RCD(max)} and t_{RAD} ≤ t_{RAD(max)}. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by amount that t_{RCD} exceeds the value shown.

10: Assumes that t_{RAD} ≥ t_{RAD(max)} and t_{ASC} ≤ t_{ASC(max)}.

11: Assumes that t_{CP} ≤ t_{CP(max)} and t_{ASC} ≥ t_{ASC(max)}.

12: t_{OEZ(max)}, t_{WEZ(max)}, t_{OFF(max)} and t_{REZ(max)} defines the time at which the output achieves the high impedance state (I_{OUT} ≤ ±10 μA) and is not reference to V_{OH(min)} or V_{OL(max)}.

13: Output is disabled after both RAS and CAS go to high.

PRELIMINARY

M5M416165CJ,TP-5,-6,-7,-5S,-6S,-7S

HYPER PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write, Refresh and Hyper-Page Mode Cycles)

(Ta=0~70°C, Vcc=5.0V±10%, Vss=0V, unless otherwise noted, see notes 14,15)

Symbol	Parameter	Limits						Unit
		M5M416165C-5,-5S		M5M416165C-6,-6S		M5M416165C-7,-7S		
		Min	Max	Min	Max	Min	Max	
tREF	Refresh cycle time		64		64		64	ms
tREF*	Refresh cycle time		128		128		128	ms
tRP	RAS high pulse width	30		40		50		ns
tRCD	Delay time, RAS low to CAS low (Note 16)	18	37	20	45	20	50	ns
tCRP	Delay time, CAS high to RAS low	5		5		5		ns
tRPC	Delay time, RAS high to CAS low	0		0		0		ns
tCPN	CAS high pulse width	8		10		10		ns
tRAD	Column address delay time from RAS low (Note 17)	13	25	15	30	15	35	ns
tASR	Row address setup time before RAS low	0		0		0		ns
tASC	Column address setup time before CAS low (Note 18)	0	10	0	13	0	13	ns
tRAH	Row address hold time after RAS low	8		10		10		ns
tCAH	Column address hold time after CAS low	8		10		10		ns
tdZC	Delay time, data to CAS low (Note 19)	0		0		0		ns
tdZO	Delay time, data to OE low (Note 19)	0		0		0		ns
tRDD	Delay time, RAS high to data (Note 20)	13		15		20		ns
tCDD	Delay time, CAS high to data (Note 20)	13		15		20		ns
tODD	Delay time, OE high to data (Note 20)	13		15		20		ns
tT	Transition time (Note 21)	1	50	1	50	1	50	ns

Note 14: The timing requirements are assumed T = 2ns.

15: VIH(min) and VIL(max) are reference levels for measuring timing of input signals.

16: tRCD(max) is specified as a reference point only. If tRCD is less than tRCD(max), access time is tRAC. If tRCD is greater than tRCD(max), access time is controlled exclusively by tCAC or tAA.

17: tRAD(max) is specified as a reference point only. If tRAD ≥ tRAD(max) and tASC ≤ tASC(max), access time is controlled exclusively by tAA.

18: tASC(max) is specified as a reference point only. If tRCD ≥ tRCD(max) and tASC ≥ tASC(max), access time is controlled exclusively by tCAC.

19: Either tdZC or tdZO must be satisfied.

20: Either tRDD or tCDD or tODD must be satisfied.

21: tT is measured between VIH(min) and VIL(max).

Read and Refresh Cycles

Symbol	Parameter	Limits						Unit
		M5M416165C-5,-5S		M5M416165C-6,-6S		M5M416165C-7,-7S		
		Min	Max	Min	Max	Min	Max	
tRC	Read cycle time	90		110		130		ns
tRAS	RAS low pulse width	50	10000	60	10000	70	10000	ns
tCAS	CAS low pulse width	8	10000	10	10000	13	10000	ns
tCSH	CAS hold time after RAS low	40		48		55		ns
tRSH	RAS hold time after CAS low	13		15		20		ns
tRCS	Read setup time before CAS high	0		0		0		ns
tRCH	Read hold time after CAS high (Note 22)	0		0		0		ns
tRRH	Read hold time after RAS high (Note 22)	10		10		10		ns
tRAL	Column address to RAS hold time	25		30		35		ns
tCAL	Column address to CAS hold time	13		18		23		ns
tORH	RAS hold time after OE low	13		15		20		ns
tOCH	CAS hold time after OE low	13		15		20		ns

Note 22: Either tRCH or tRRH must be satisfied for a read cycle.



Write Cycle (Early Write and Delayed Write)

Symbol	Parameter	Limits						Unit
		M5M416165C-5,-5S		M5M416165C-6,-6S		M5M416165C-7,-7S		
		Min	Max	Min	Max	Min	Max	
tWC	Write cycle time	90		110		130		ns
tRAS	RAS low pulse width	50	10000	60	10000	70	10000	ns
tCAS	CAS low pulse width	8	10000	10	10000	13	10000	ns
tCSH	CAS hold time after RAS low	40		48		55		ns
tRSH	RAS hold time after CAS low	13		15		20		ns
tWCS	Write setup time before CAS low (Note 24)	0		0		0		ns
tWCH	Write hold time after CAS low	8		10		13		ns
tCWL	CAS hold time after W low	8		10		13		ns
tRWL	RAS hold time after W low	8		10		13		ns
tWP	Write pulse width	8		10		13		ns
tDS	Data setup time before CAS low or W low	0		0		0		ns
tDH	Data hold time after CAS low or W low	8		10		13		ns

Read-Write and Read-Modify-Write Cycles

Symbol	Parameter	Limits						Unit
		M5M416165C-5,-5S		M5M416165C-6,-6S		M5M416165C-7,-7S		
		Min	Max	Min	Max	Min	Max	
tRWC	Read write/read modify write cycle time (Note 23)	109		133		161		ns
tRAS	RAS low pulse width	75	10000	89	10000	107	10000	ns
tCAS	CAS low pulse width	38	10000	44	10000	57	10000	ns
tCSH	CAS hold time after RAS low	70		82		99		ns
tRSH	RAS hold time after CAS low	38		44		57		ns
tRCS	Read setup time before CAS low	0		0		0		ns
tCWD	Delay time, CAS low to W low (Note 24)	28		32		42		ns
tRWD	Delay time, RAS low to W low (Note 24)	65		77		92		ns
tAWD	Delay time, address to W low (Note 24)	40		47		57		ns
tOEH	OE hold time after W low	13		15		20		ns

Note 23: tRWC is specified as $tRWC(\min) = tRAC(\max) + tODD(\min) + tRWL(\min) + tRP(\min) + 4t$.

24: tWCS, tCWD, tRWD and tAWD and, tCPWD are specified as reference points only. If $tWCS \geq tWCS(\min)$ the cycle is an early write cycle and the DQ pins will remain high impedance throughout the entire cycle. If $tCWD \geq tCWD(\min)$, $tRWD \geq tRWD(\min)$, $tAWD \geq tAWD(\min)$ and $tCPWD \geq tCPWD(\min)$ (for hyper page mode cycle only), the cycle is a read-modify-write cycle and the DQ will contain the data read from the selected address. If neither of the above condition (delayed write) of the DQ (at access time and until CAS or OE goes back to VIH) is indeterminate.

PRELIMINARY

Note: This is not a final specification.
Some parameters limits are subject to change.

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hyper page Mode Cycle

(Read, Early Write, Read-Write, Read-Modify-Write Cycle, Read Write Mix Cycle, HI-Z control by \overline{OE} or \overline{W}) (Note 25)

Symbol	Parameter	Limits						Unit
		M5M416165C-5,-5S		M5M416165C-6,-6S		M5M416165C-7,-7S		
		Min	Max	Min	Max	Min	Max	
tHPC	Hyper page mode read/write cycle time	20		25		30		ns
tHPRWC	Hyper page mode read write/read modify write cycle time	57		66		79		ns
tDOH	Output hold time from \overline{CAS} low	5		5		5		ns
tRAS	\overline{RAS} low pulse width for read write cycle (Note 26)	65	100000	77	100000	92	100000	ns
tCP	\overline{CAS} high pulse width (Note 27)	8	13	10	16	10	16	ns
tCPRH	\overline{RAS} hold time after \overline{CAS} precharge	30		35		40		ns
tCPWD	Delay time, \overline{CAS} precharge to \overline{W} low (Note 24)	45		52		62		ns
tCHOL	Hold time to maintain the data HI-Z until \overline{CAS} access	7		7		7		ns
tOEPE	\overline{OE} Pulse width (HI-Z control)	7		7		7		ns
tWPE	\overline{W} Pulse width (HI-Z control)	7		7		7		ns
tHCWD	Delay time, \overline{CAS} low to \overline{W} low after read	28		32		42		ns
tHAWD	Delay time, address to \overline{W} low after read	52		62		72		ns
tHPWD	Delay time, \overline{CAS} precharge to \overline{W} low after read	62		72		82		ns
tHCOD	Delay time, \overline{CAS} low to \overline{OE} high after read	13		15		20		ns
tHAOD	Delay time, address to \overline{OE} high after read	25		30		35		ns
tHPOD	Delay time, \overline{CAS} precharge to \overline{OE} high after read	30		35		40		ns

Note 25: All previously specified timing requirements and switching characteristics are applicable to their respective Hyper page mode cycle.

26: tRAS(min) is specified as two cycles of \overline{CAS} input are performed.

27: tCP(max) is specified as a reference point only.

\overline{CAS} before \overline{RAS} Refresh Cycle (Note 28)

Symbol	Parameter	Limits						Unit
		M5M416165C-5,-5S		M5M416165C-6,-6S		M5M416165C-7,-7S		
		Min	Max	Min	Max	Min	Max	
tCSR	\overline{CAS} setup time before \overline{RAS} low	5		5		5		ns
tCHR	\overline{CAS} hold time after \overline{RAS} low	10		10		15		ns

Note 28: Eight or more \overline{CAS} before \overline{RAS} cycles instead of eight \overline{RAS} cycles are necessary for proper operation of \overline{CAS} before \overline{RAS} refresh mode.

SELF REFRESH SPECIFICATIONS

Self refresh devices are denoted by 'S' after speed item, like -5S/ -6S/ -7S. The other characteristics and requirements than the below are same as normal devices.

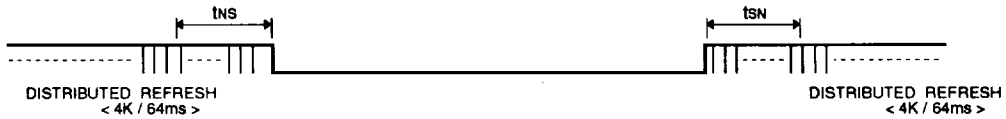
TIMING REQUIREMENTS (Ta=0~70°C, Vcc=5.0V±10%, Vss=0V, unless otherwise noted, see notes 13,14)

Symbol	Parameter	Limits						Unit
		M5M416165C-5S		M5M416165C-6S		M5M416165C-7S		
		Min	Max	Min	Max	Min	Max	
t _{RASS}	Self refresh \overline{RAS} low pulse width	100		100		100		μs
t _{RPS}	Self refresh \overline{RAS} high precharge time	90		110		130		ns
t _{CHS}	Self refresh \overline{RAS} hold time	- 50		- 50		- 50		ns

SELF REFRESH ENTRY & EXIT CONDITIONS

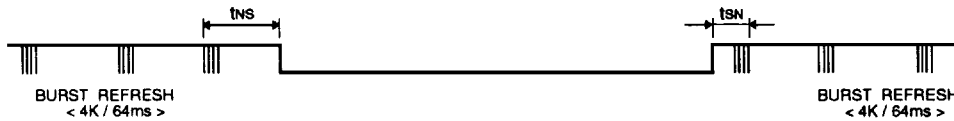
(1) In case of distributed refresh

The last / first full refresh cycles (4K) must be made within t_{NS} / t_{SN} before / after self refresh, on the condition of t_{NS} ≤ 64ms and t_{SN} ≤ 64ms.



(2) In case of burst refresh

The last / first full refresh cycles (4K) must be made within t_{NS} / t_{SN} before / after self refresh, on the condition of t_{NS} + t_{SN} ≤ 64ms.



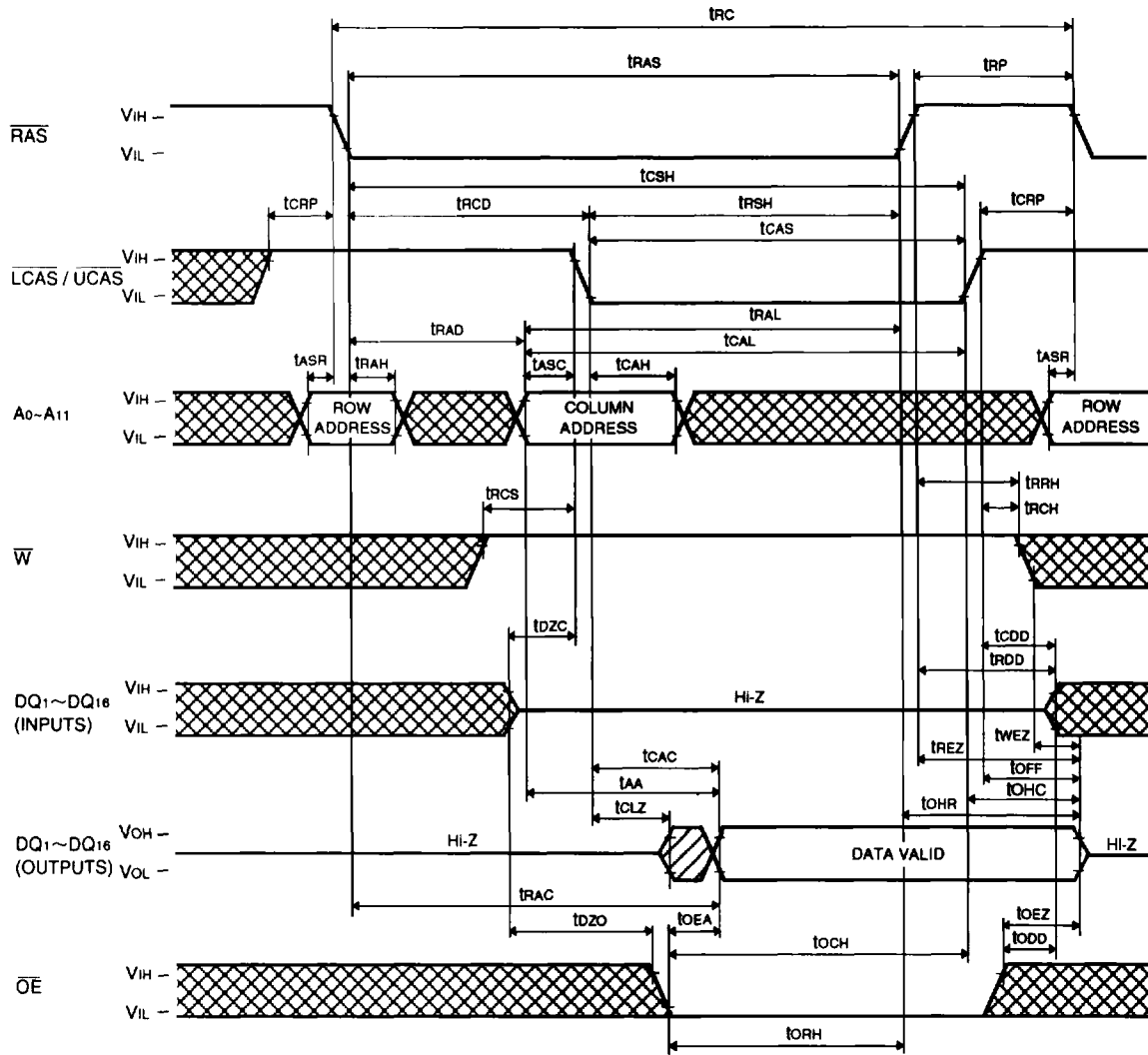
PRELIMINARY

M5M416165CJ, TP-5, -6, -7, -5S, -6S, -7S


HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM


Timing Diagrams (Note 29)

Read Cycle



Note 29

 Indicates the don't care input.
 $V_{IH(min)} \leq V_{IN} \leq V_{IH(max)}$ or $V_{IL(min)} \leq V_{IN} \leq V_{IL(max)}$

 Indicates the invalid output.

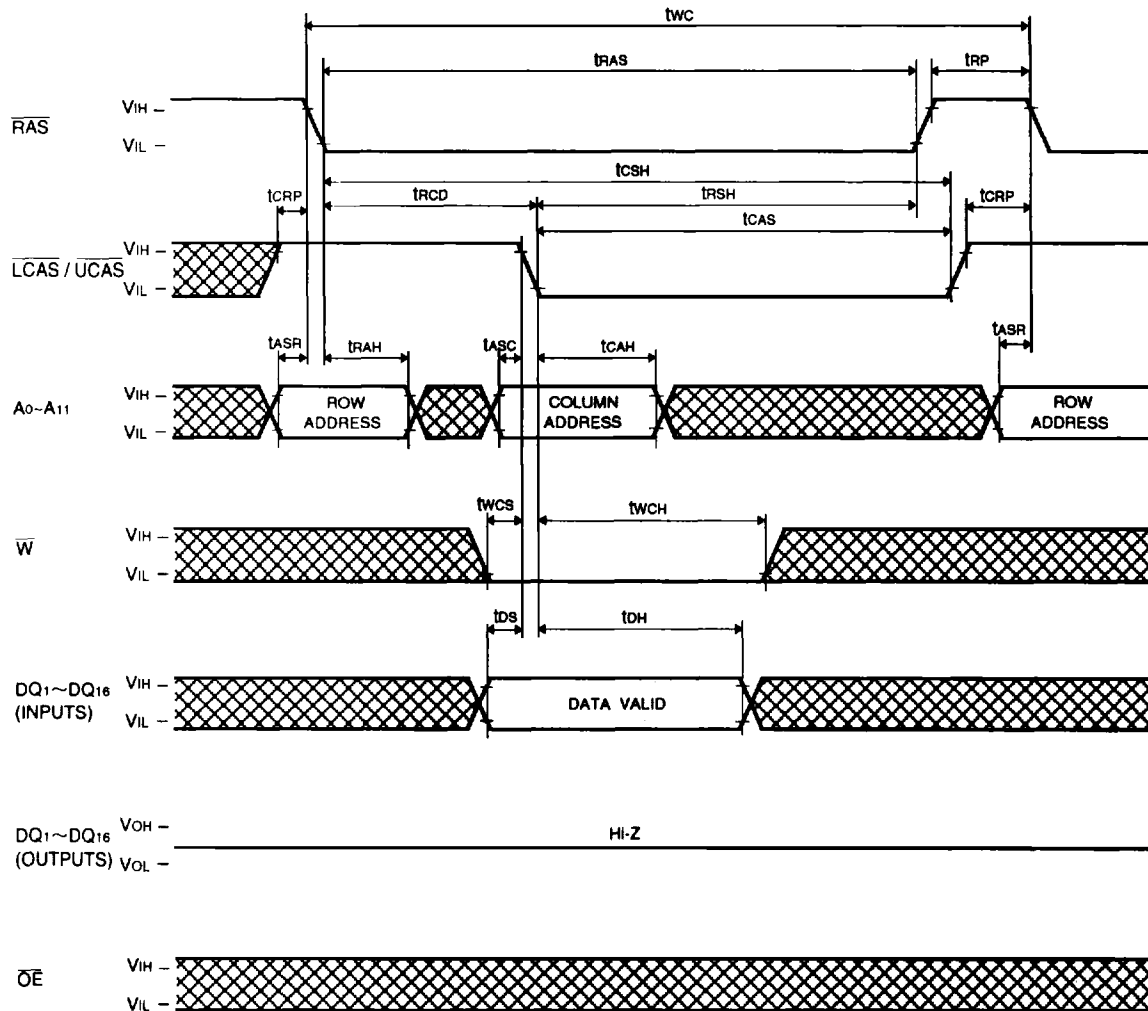
PRELIMINARY

For the latest information, please refer to the latest version of the data sheet.

MITSUBISHI LSI[®] M5M416165CJ,TP-5,-6,-7,-5S,-6S,-7S

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Early Write Cycle



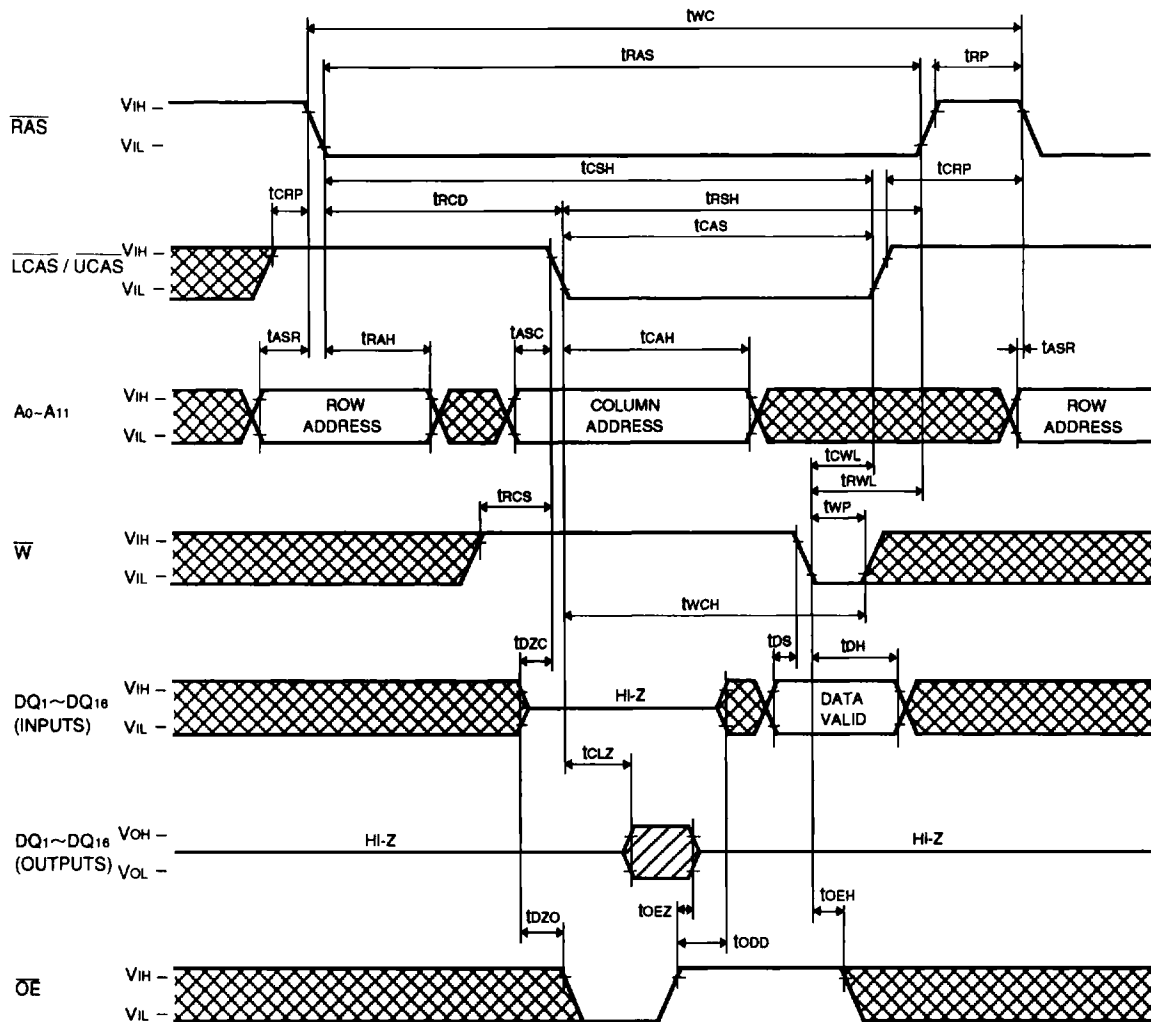
PRELIMINARY

M5M416165CJ, TP-5, -6, -7, -5S, -6S, -7S

Notice: This is not a final specification.
Some parameter limits are subject to change.

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Delayed Write Cycle

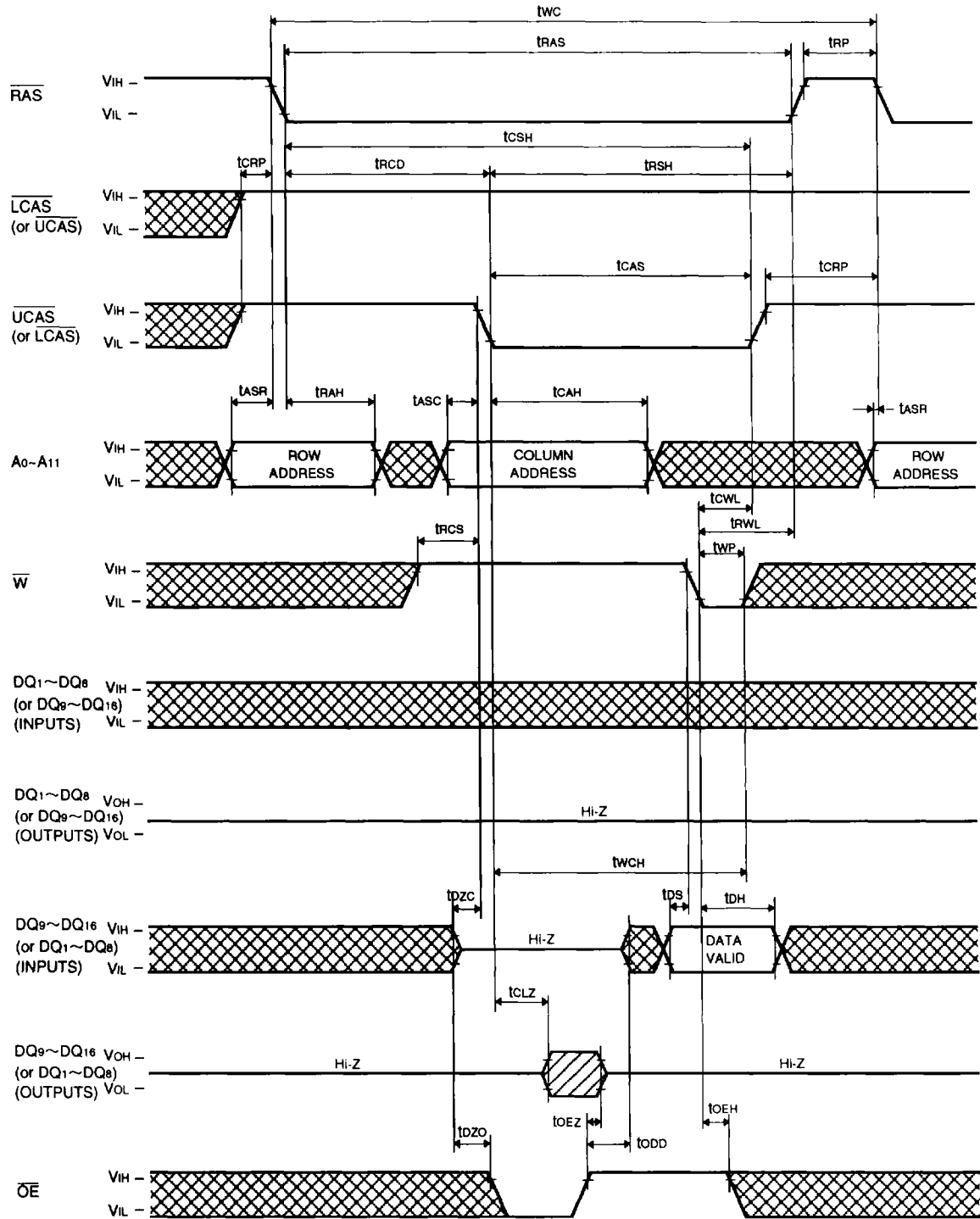


PRELIMINARY

M5M416165CJ,TP-5,-6,-7,-5S,-6S,-7S

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Byte Delayed Write Cycle

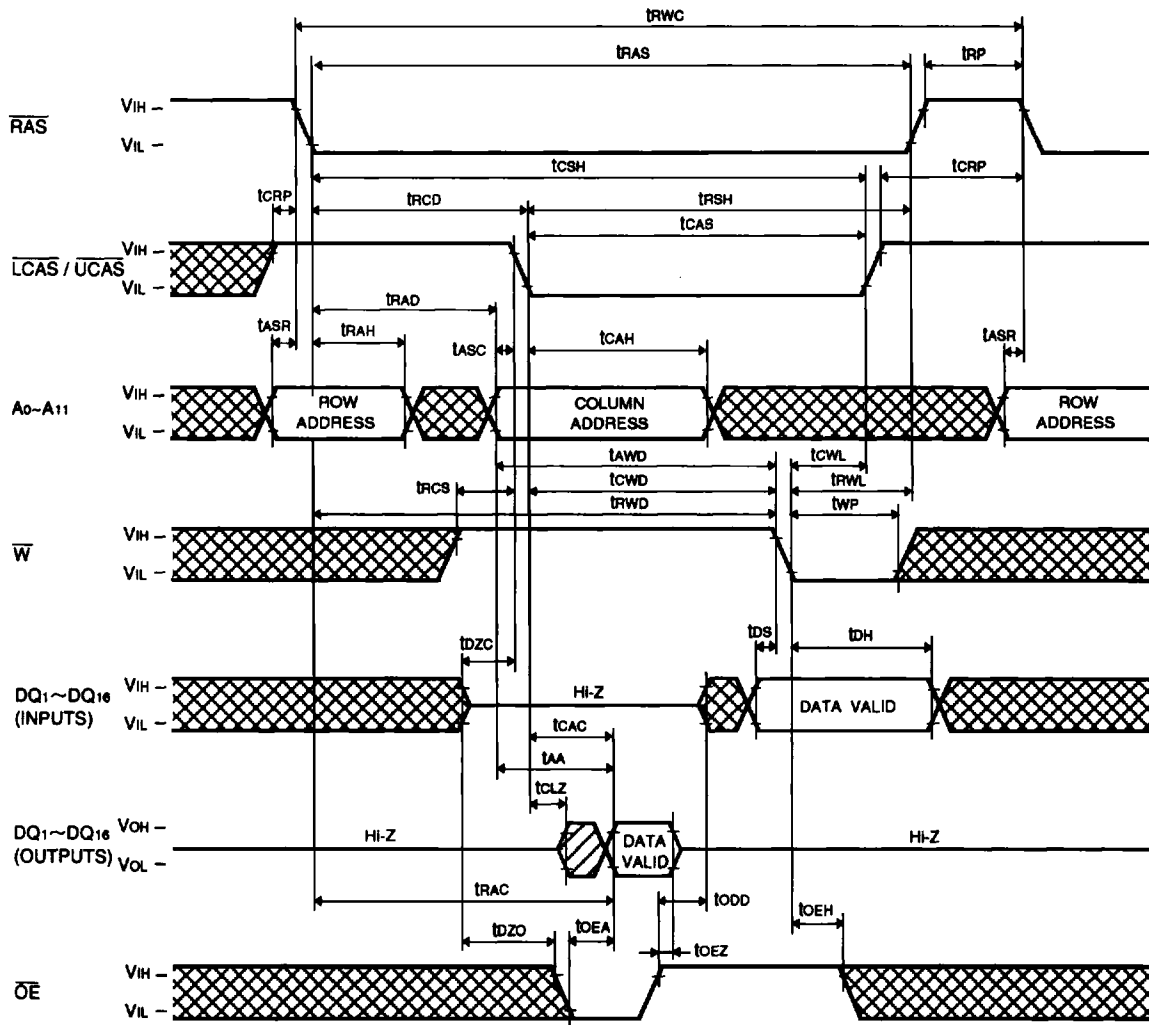


PRELIMINARY

Notice: This is not a final specification.
Some parametric limits are subject to change

HYPER PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Read-Write, Read-Modify-Write Cycle

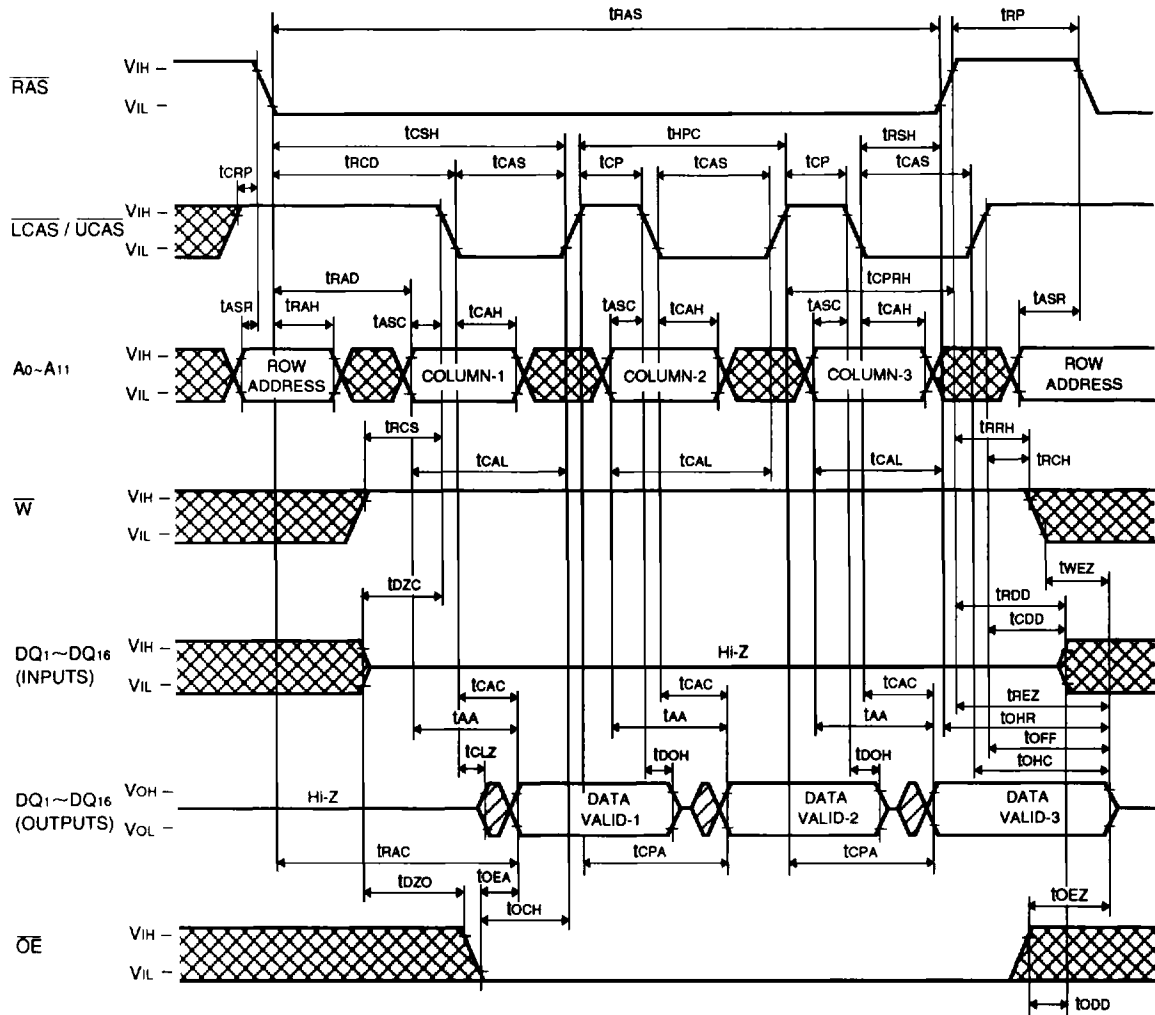


PRELIMINARY

Note: 1. This is a preliminary specification.
2. Some parameters may be subject to change.

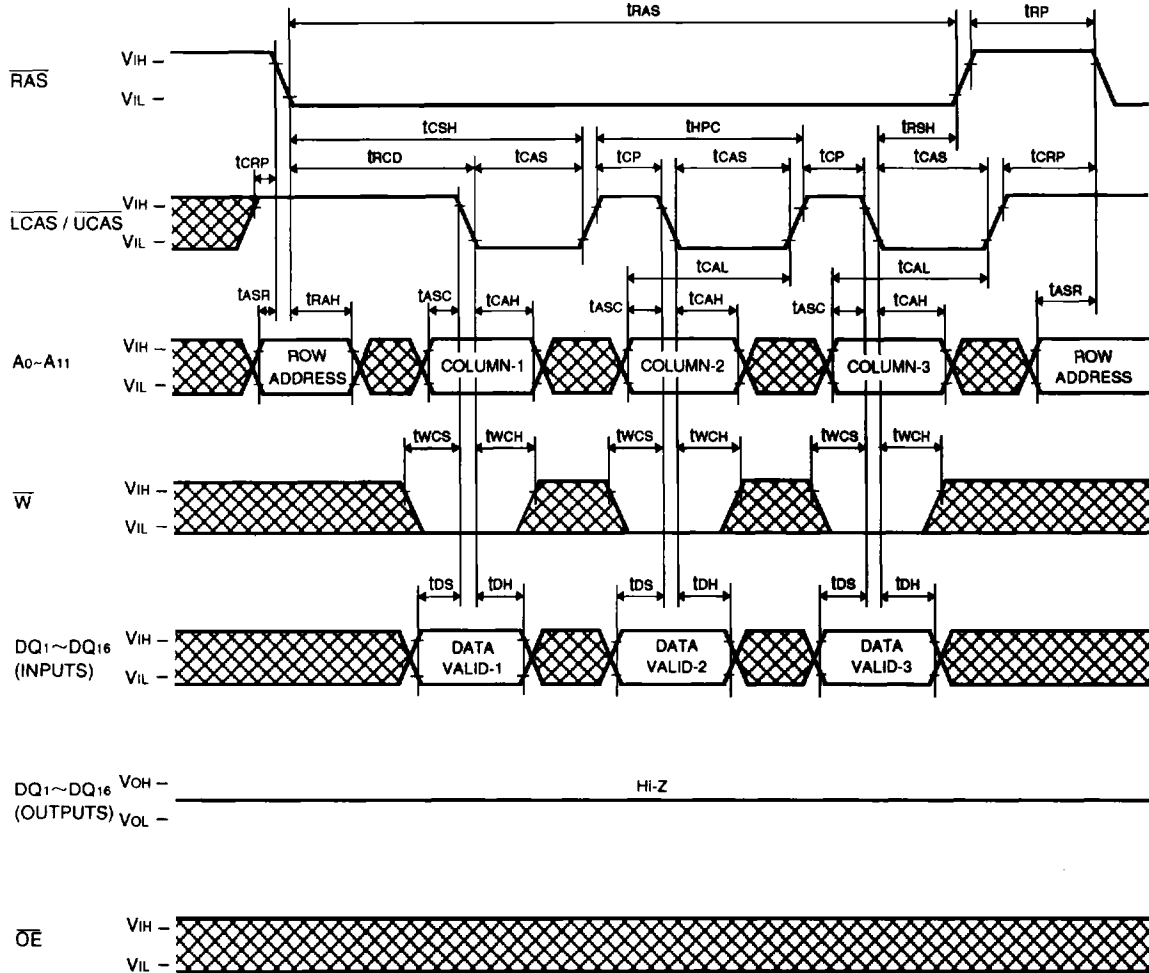
HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hyper Page Mode Read Cycle

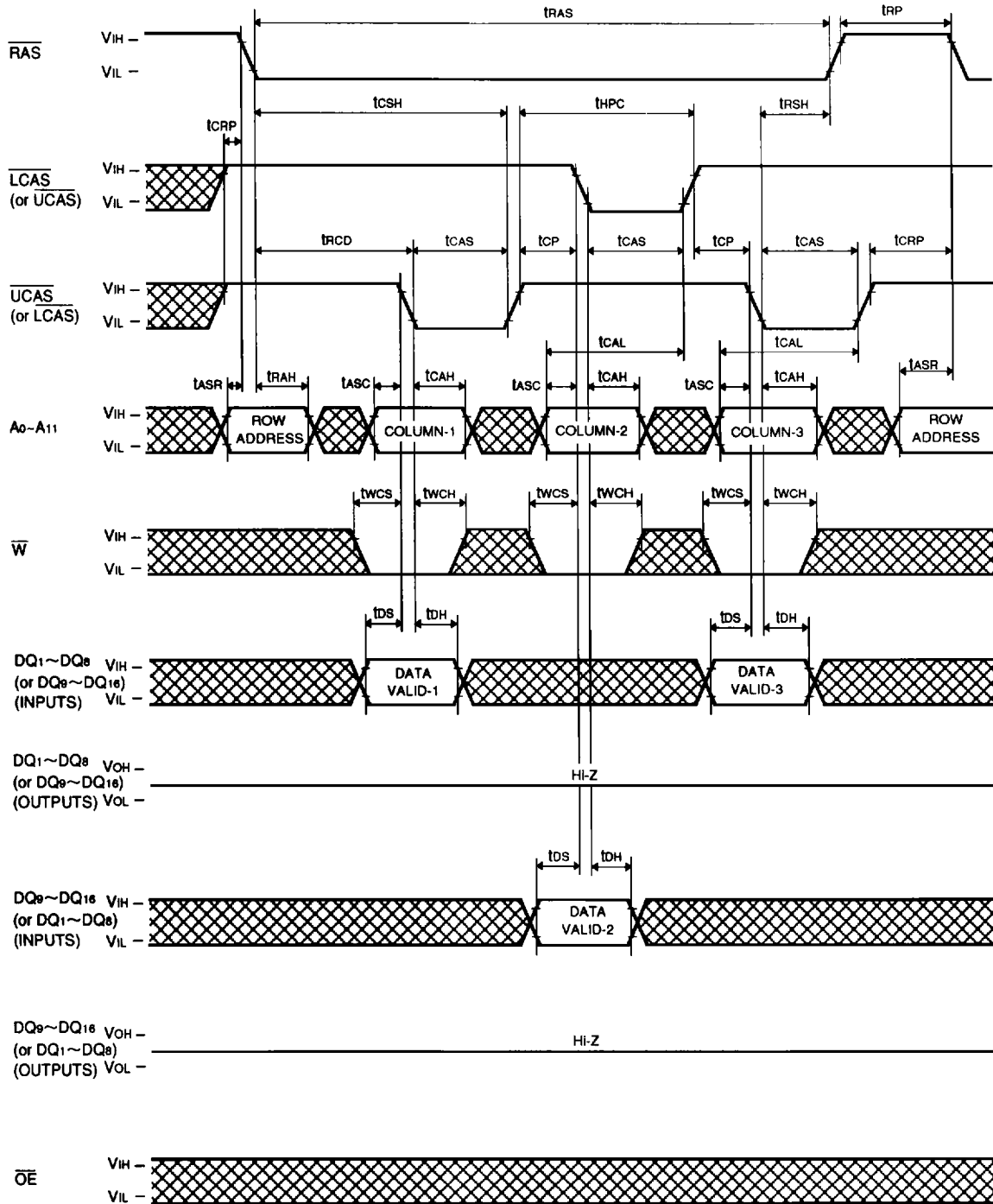


HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hyper Page Mode Early Write Cycle



Hyper Page Mode Byte Early Write Cycle



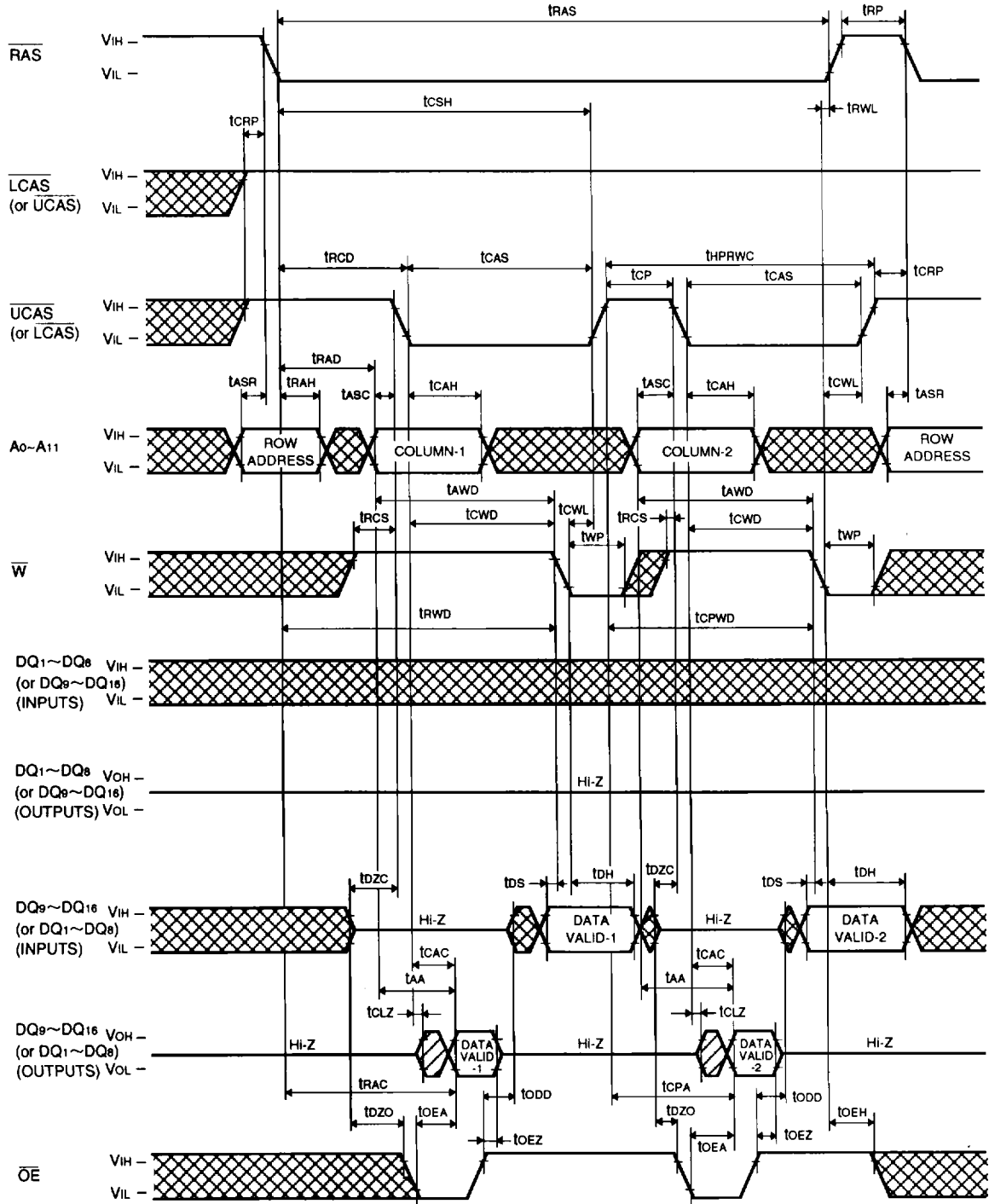
PRELIMINARY

Note: This is not a final specification.
Some parameters are subject to change.

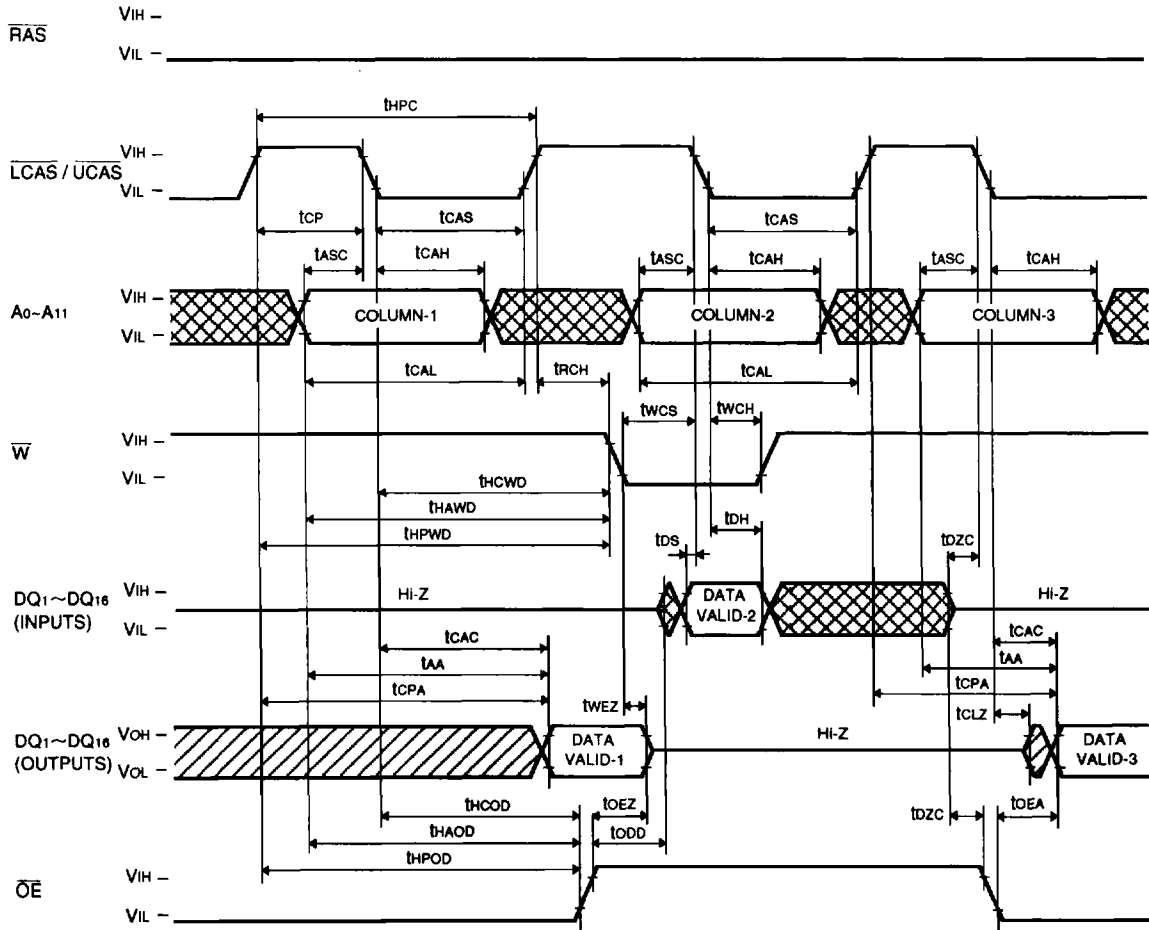
MITSUBISHI LSIs
M5M416165CJ,TP-5,-6,-7,-5S,-6S,-7S

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hyper Page Mode Byte Read-Write, Read-Modify-Write Cycle



Hyper Page Mode Mix Cycle (2)



PRELIMINARY

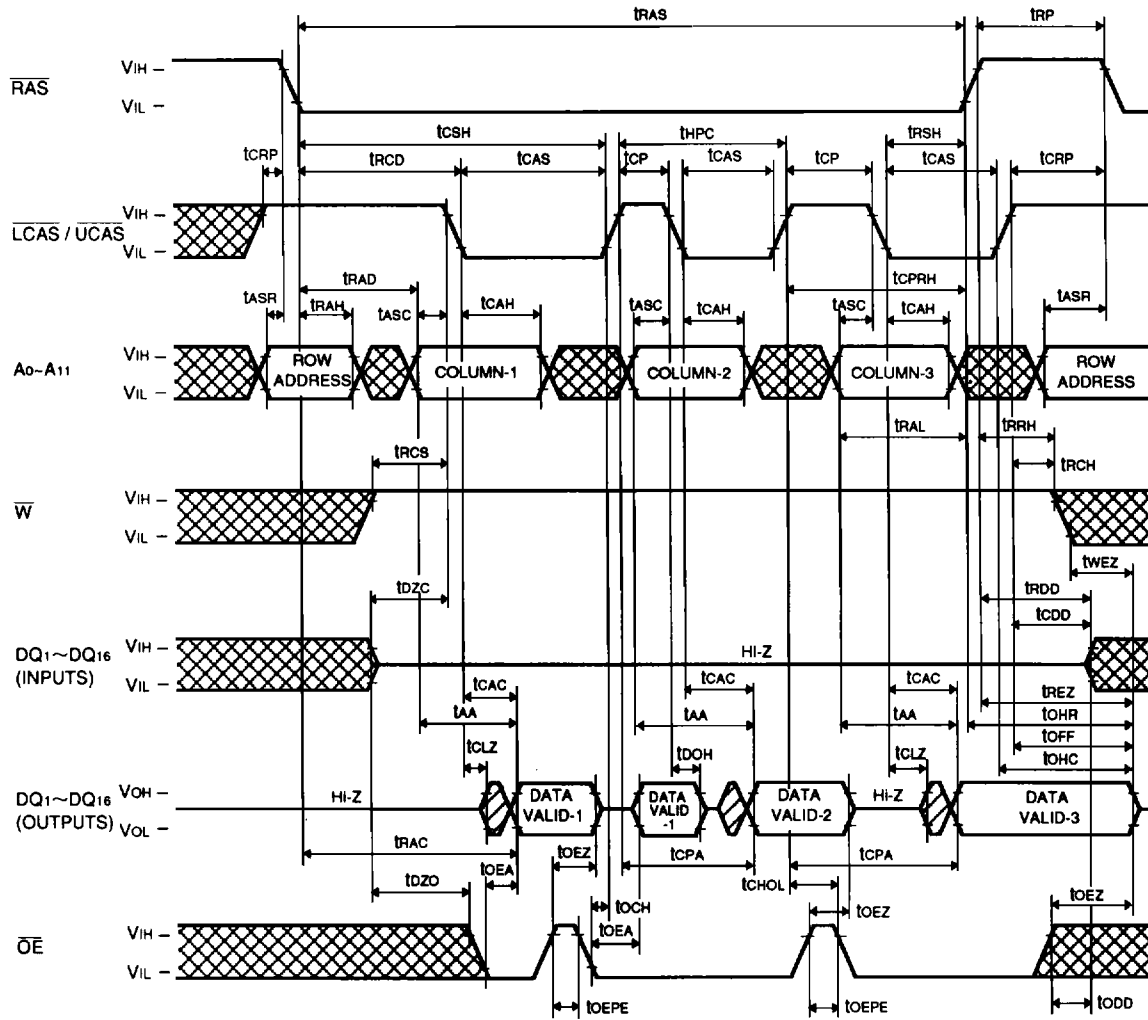
Note: This is not a final specification.
Some parameter limits are subject to change.

MITSUBISHI LSIs

M5M416165CJ, TP-5, -6, -7, -5S, -6S, -7S

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hyper Page Mode Read Cycle (Hi-Z control by \overline{OE})



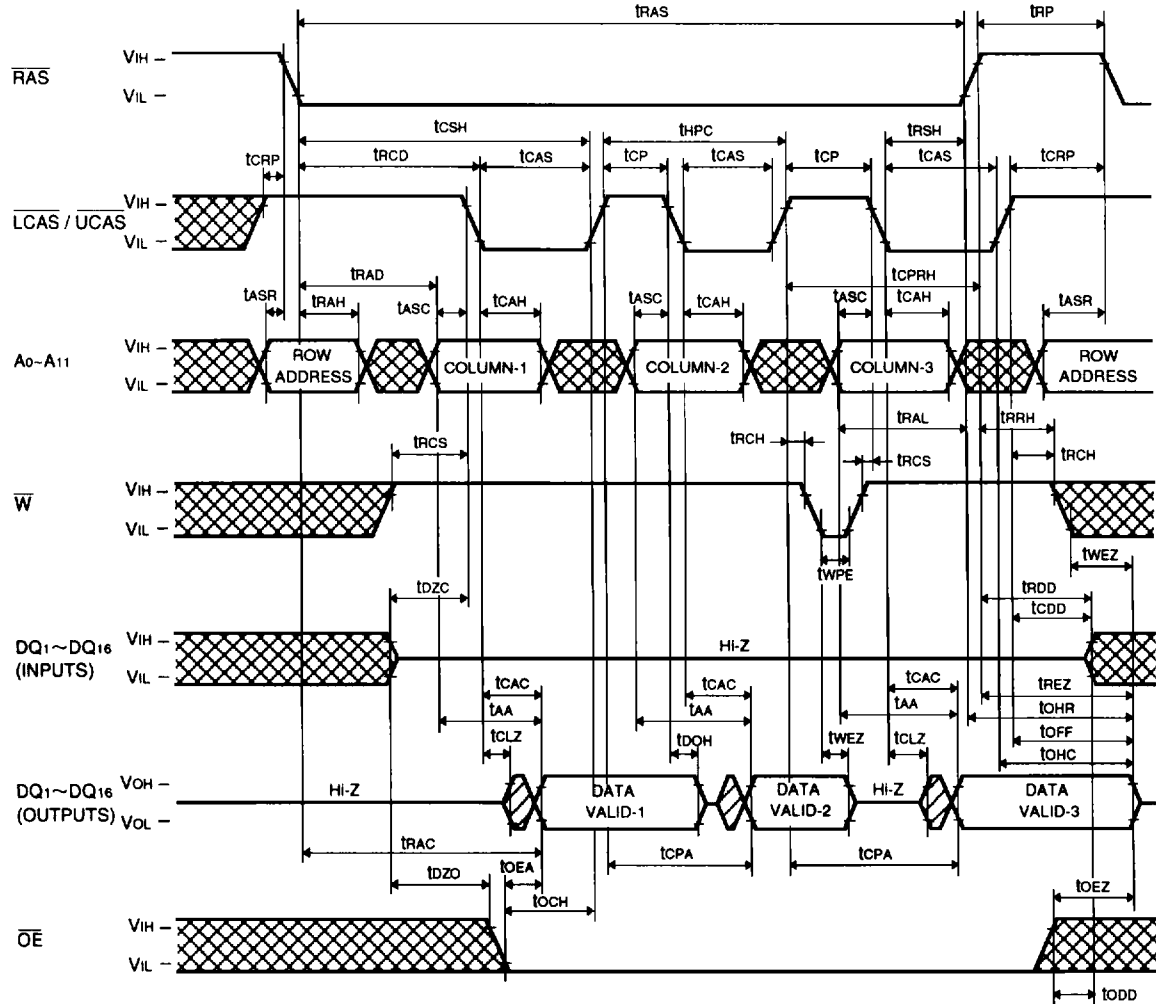
PRELIMINARY

M5M416165CJ, TP-5,-6,-7,-5S,-6S,-7S

Note: This is a preliminary drawing.
Some parameter values are subject to change.

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hyper Page Mode Read Cycle (HI-Z control by \overline{W})

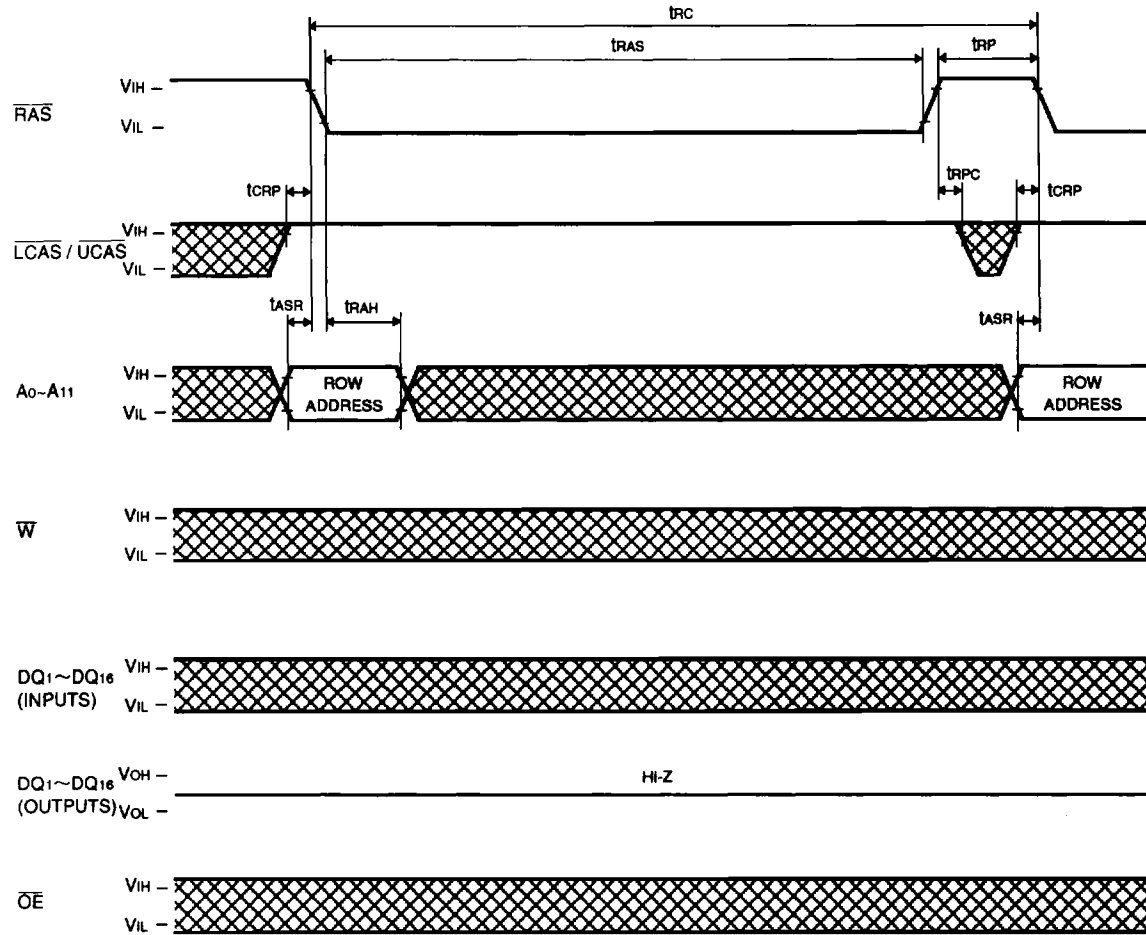


PRELIMINARY

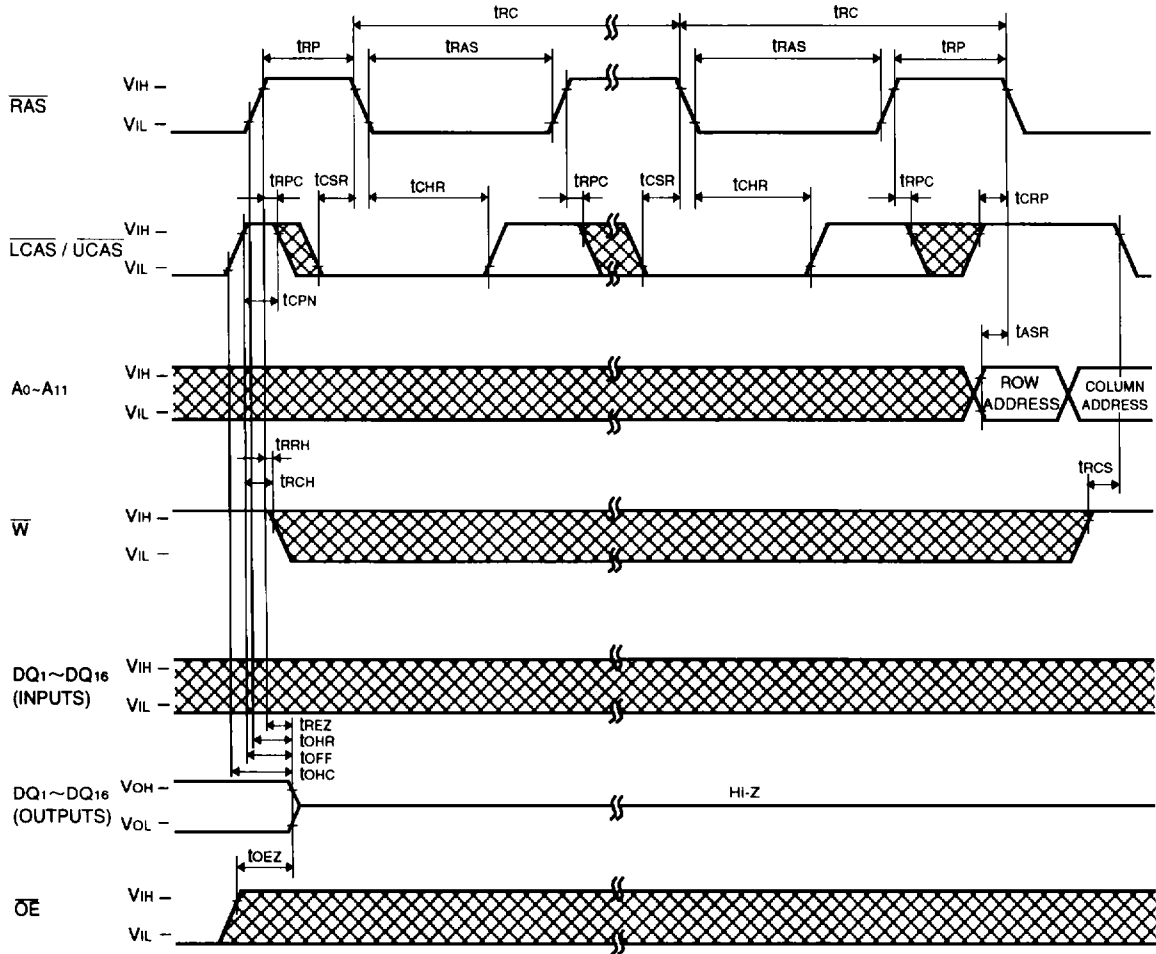
Note: This is not a final specification. Some parameter limits are subject to change.

HYPER PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

RAS-only Refresh Cycle



CAS before RAS Refresh Cycle, Extended Refresh Cycle*



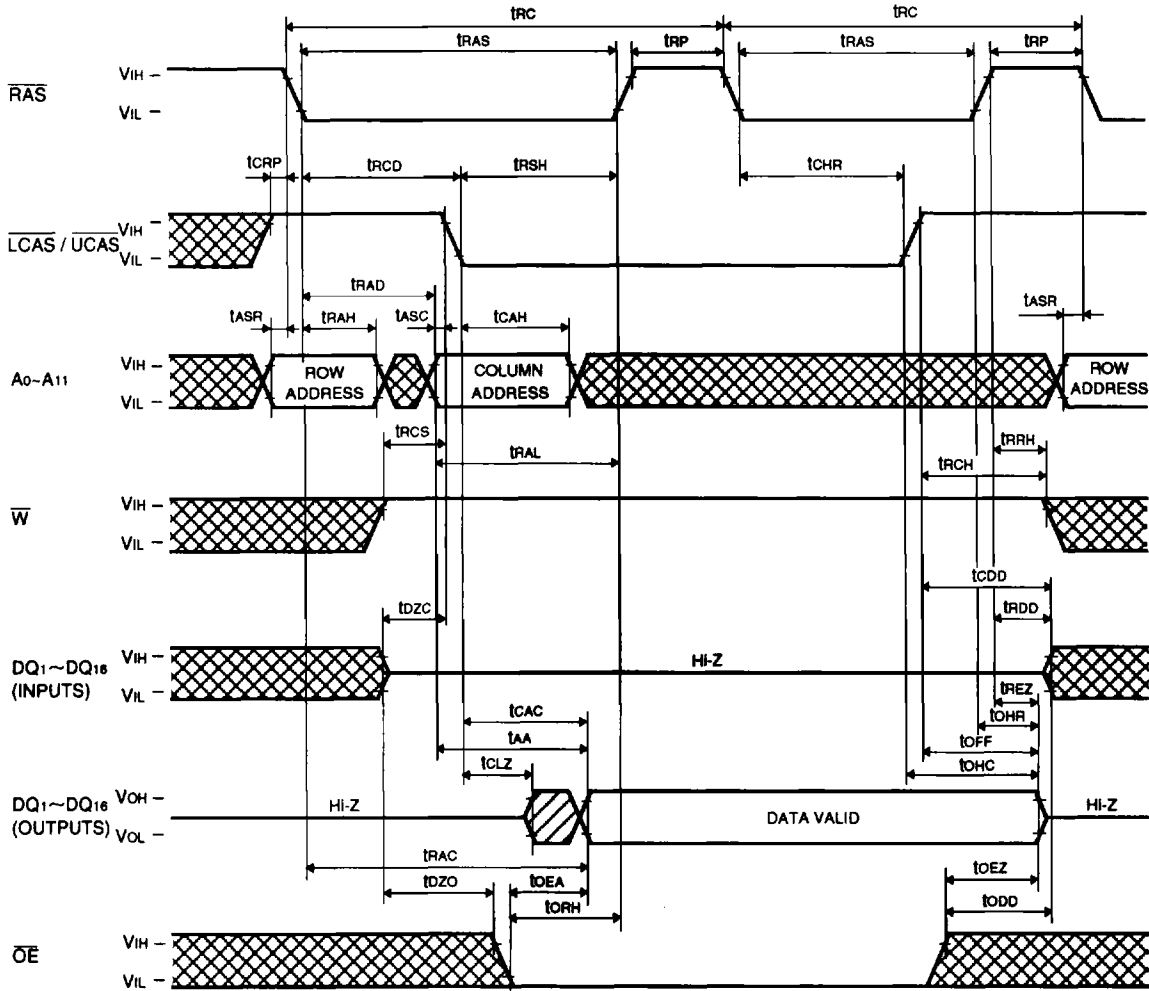
PRELIMINARY

M5M416165CJ, TP-5, -6, -7, -5S, -6S, -7S

Note: This is not a final specification.
Some parameter limits are subject to change.

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hidden Refresh Cycle (Read) (Note 30)



Note 30: Early write, delayed write, read write or read modify write cycle is applicable instead of read cycle. Timing requirements and output state are the same as that of each cycle shown above.

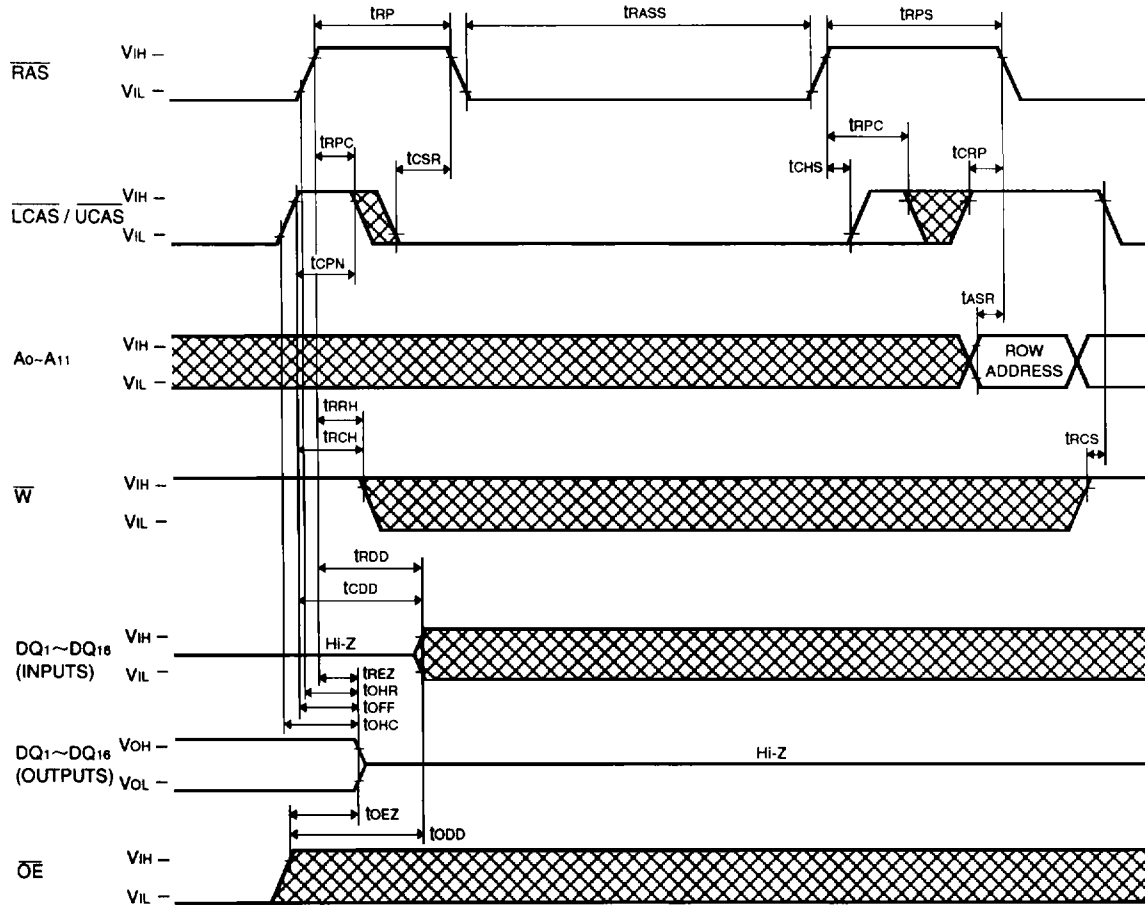
PRELIMINARY

M5M416165CJ,TP-5,-6,-7,-5S,-6S,-7S

Note: This circuit is for a preliminary design. Some parameters may change without notice.

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Self Refresh Cycle *



PRELIMINARY

Notice: This is not a final specification.
Some parametric limits are subject to change.

HYPER PAGE MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper / (Lower) Self Refresh Cycle*

